

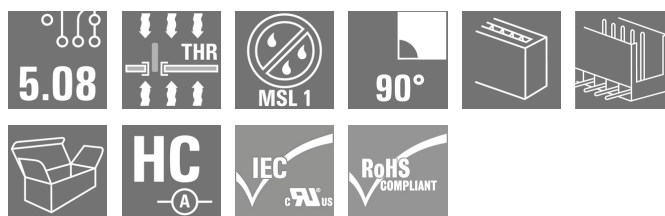
SL-SMT 5.08HC/18/90V 3.2AU BK BX SO ABB**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



Similar to illustration

High-temperature-resistant, straight, open pin header.
Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 5.08 mm, Number of poles: 18, 90°, Solder pin length (l): 3.2 mm, Au (Gold), black, Box
Order No.	1004230000
Type	SL-SMT 5.08HC/18/90V 3.2AU BK BX SO ABB
GTIN (EAN)	4032248703036
Qty.	20 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

Creation date November 7, 2024 4:21:27 AM CET

SL-SMT 5.08HC/18/90V 3.2AU BK BX SO ABB**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Technical data**Dimensions and weights**

Depth	12 mm	Depth (inches)	0.472 inch
Height	11.7 mm	Height (inches)	0.461 inch
Height of lowest version	8.5 mm	Width	91.44 mm
Width (inches)	3.6 inch	Net weight	8.35 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 "	Outgoing elbow	90°
Number of poles	18	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		L1 in mm	86.36 mm
L1 in inches	3.4 "	Number of rows	1
Pin series quantity	1	Touch-safe protection acc. to DIN VDE 57 106	finger-safe unplugged/ back-of-hand-safe plugged
Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged	Protection degree	IP20
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	9 N	Pulling force/pole, max.	7 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface	Au (Gold)	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn / 1.7...2.3 µm Au	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

SL-SMT 5.08HC/18/90V 3.2AU BK BX SO ABB**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Technical data**Rated data acc. to CSA**

Rated voltage (Use group B / CSA)	300 V
Rated current (Use group B / CSA)	18.5 A

Rated voltage (Use group D / CSA)	300 V
Rated current (Use group D / CSA)	18.5 A

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated current (Use group B / UL 1059) 18.5 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group D / UL 1059) 10 A

Packing

Packaging	Box	VPE length	219 mm
VPE width	64 mm	VPE height	48 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01		

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

SL-SMT 5.08HC/18/90V 3.2AU BK BX SO ABB**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**Technical data****Important note**

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet $D = 1.4 \pm 0.1 \text{ mm}$ • Solder eyelet diameter $D = 1.5 \pm 0.1 \text{ mm}$, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load • Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

Approvals

Approvals



ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Catalogues	Catalogues in PDF-format
White paper surface mount technology	Download Whitepaper

SL-SMT 5.08HC/18/90V 3.2AU BK BX SO ABB

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

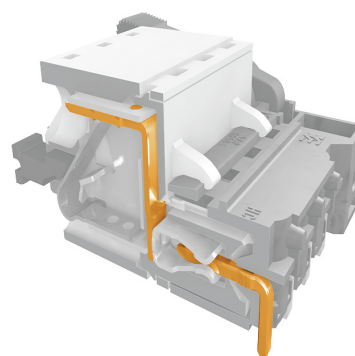
D-32758 Detmold

Germany

www.weidmueller.com

Drawings

Product benefits



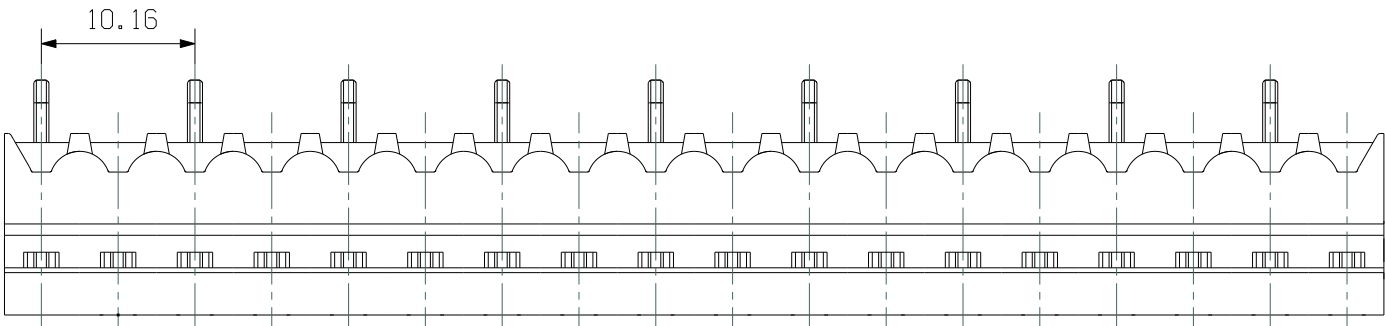
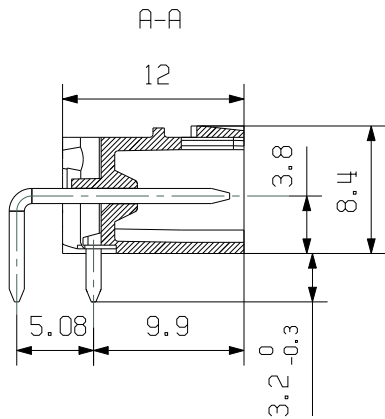
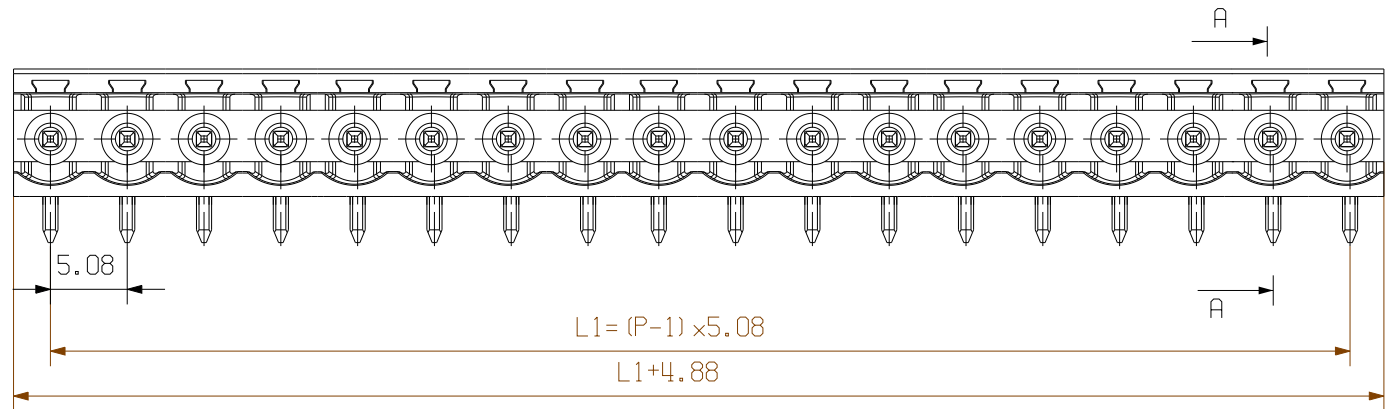
Safe power transmission
Proven properties

The reproduction, distribution and utilization of this document as well as the communication of its contents to others without explicit authorization is prohibited. Offenders will be held liable for the payment of damages. Weidmueller exclusively reserves the right to file for patents, utility models or designs.

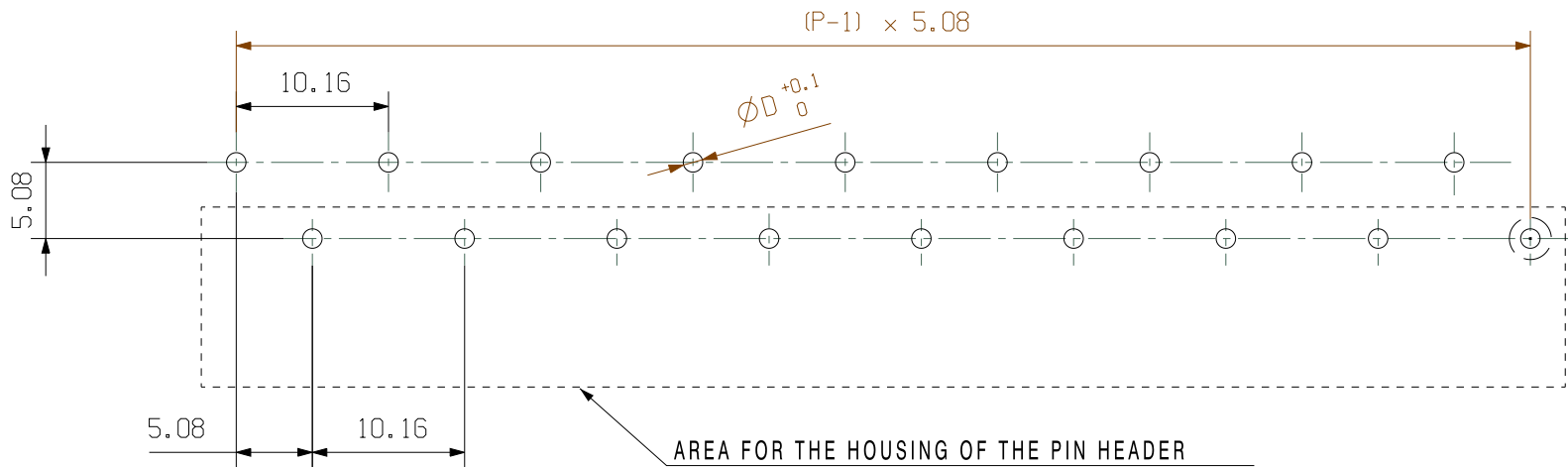
© Weidmueller Interface GmbH & Co. KG

Dimensions without tolerances are no check dimensions

The English version is binding



HOLE PATTERN
LAYOUTTOLERANCE ACC. IEC 326 PART 3



24	116,84	4,600
23	111,76	4,400
22	106,68	4,200
21	101,60	4,000
20	96,52	3,800
19	91,44	3,600
18	86,36	3,400
17	81,28	3,200
16	76,20	3,000
15	71,12	2,800
14	66,04	2,600
13	60,96	2,400
12	55,88	2,200
11	50,80	2,000
10	45,72	1,800
9	40,64	1,600
8	35,56	1,400
7	30,48	1,200
6	25,40	1,000
5	20,32	0,800
4	15,24	0,600
3	10,16	0,400
2	5,08	0,200
n	L1 [mm]	L1 [Inch]

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone.
The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.
The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.
Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

SHOWN:SL-SMT5.08HC/18/90V

D= 1,4mm BIS POLZAHL 8 /TILL POLE 8
D= 1,5mm AB POLZAHL 9-24 /FROM POLE 9-24

	DIN ISO 2768-m		85354/2 13.12.16 HERTEL_S 01		Cat.no.: .	
	Modification		Date		Name	
	Drawn	26.06.2007	HERTEL_S		Weidmüller	
	Responsible		HERTEL_S			
Scale: 2:1	Checked	14.12.2016	HELIS_MA			
Supersedes: .	Approved		LANG_T		Product file: SL-SMT 5.08	

SL-SMT 5.08HC/././90V...
STIFTLISTE
MALE HEADER

7313

3 42516 10

Drawing no. Issue no.

Sheet 01 of 01 sheets

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.